Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3	(JP-11307586-$ or JP-11204720-$ or JP-05251616-$).did.	DERWENT	OR	OFF	2004/09/12 10:30
S3	1	(((("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.) and groove	US-PGPUB; USPAT	OR	OFF	2004/09/12 10:33
S4	0	((((("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.) and groove) and (11-307586 or 11-204720 or 05-251616 or 5-251616)	US-PGPUB; USPAT	OR	OFF	2004/09/12 10:33
S5	6878	(bend bending bended) and silicon and (groove trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/12 11:07
S6	3734	(bend bending bended) and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/12 11:08
S7	1399	((bend bending bended) and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/12 11:08
S8	94	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/12 12:24
S9	289	(bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/12 11:08
S10	195	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) not (((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/12 13:24
S11	2	"4984063"	US-PGPUB; USPAT	OR	OFF	2004/09/12 14:49
S12	19	"3860949"	US-PGPUB; USPAT	OR	OFF	2004/09/12 14:53
S13	13	"3860949" and silicon	US-PGPUB; USPAT	OR	OFF	2004/09/12 14:53

S15	3	(US-5912427-$ or US-4905575-$).did. or (US-20010012035-$).did.	US-PGPUB; USPAT	OR	OFF	2004/09/13 11:13
S21	4	(("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:18
S22	181	(257/668,669,674,738).CCLS. and @pd>"20040912"	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:18
S23	3	(JP-11307586-$ or JP-11204720-$ or JP-05251616-$).did.	DERWENT	OR	OFF	2005/02/08 18:19
S24	1	((("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.) and groove	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:19
S25	0	(((("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.) and groove) and (11-307586 or 11-204720 or 05-251616 or 5-251616)	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:19
S26	7454	(bend bending bended) and silicon and (groove trench)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:19
S27	4063	(bend bending bended) and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:19
S28	1502	((bend bending bended) and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:19
S29	109	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:19
S30	318	(bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:19
S31	209	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) not (((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:19
S32	2	"4984063"	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:19

S33	20	"3860949"	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:19
S34	14	"3860949" and silicon	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:19
S35	3	(US-5912427-$ or US-4905575-$).did. or (US-20010012035-$).did.	US-PGPUB; USPAT	OR	OFF	2005/02/08 18:19
S36	1	WO-200079288-$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 18:21